

PCB Fabrication Notes

Unless otherwise specified, all dimensions are in inches

Overall Dimension: 3.330" x 2.6"

Finished Thickness: .062"

Layer Count: 4

Drill Count: 586

PAD Count: 729

Solder Mask: RED LPI

Legend: White Non-Conductive Ink LPI Process

RS274-X Gerber Format, 2.5 Leading Zeros Suppressed

Excellon Drill Format, 2.5 Trailing Zeros Suppressed

Layer Details

POLARITY

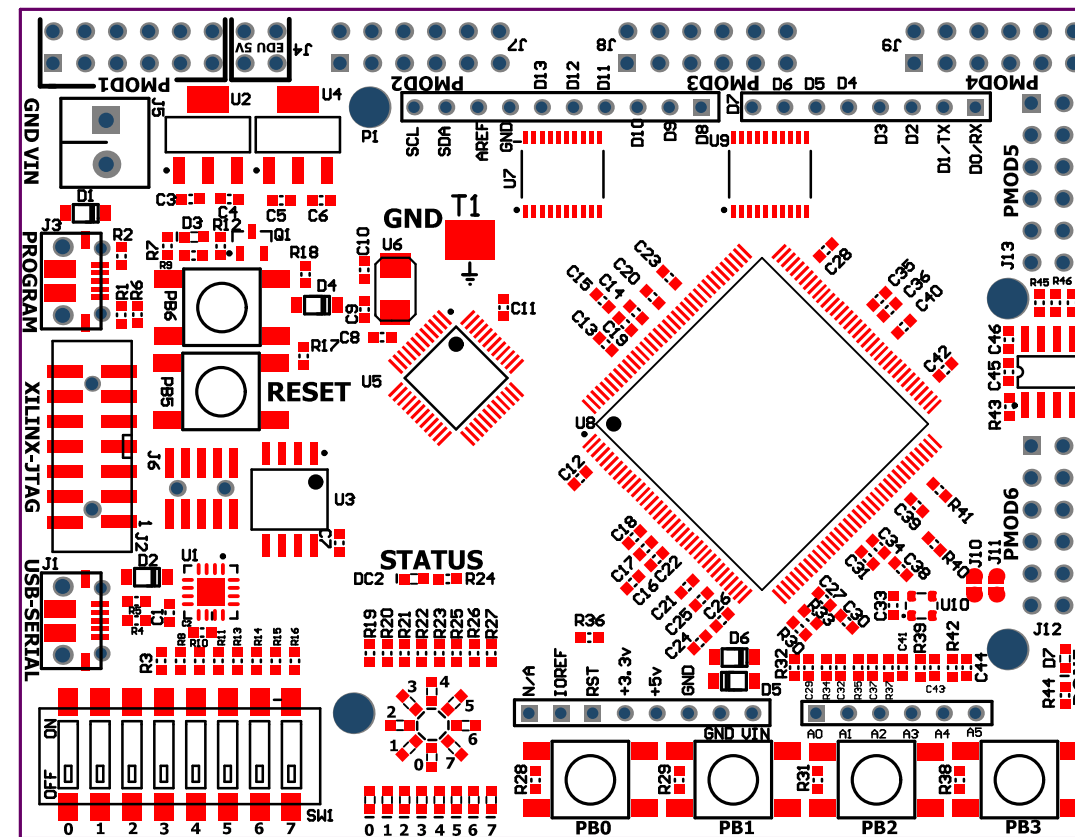
.GTL Top Copper
.G1 Inner Copper
.G2 INNER COPPER
.GBL Bottom Copper

POSITIVE
POSITIVE
POSITIVE
POSITIVE

4-Layer Stackup

.GTO Top Silkscreen
.GBO Bottom Silkscreen
.GTP Top Paste Mask
.GBP Bottom Paste Mask'
.GTS Top Soldermask
.GBS Bottom Soldermask
.TXT NC-DRILL
.GM5 BOARD OUTLINE

ASSEMBLY DRAWING - TOP



ASSEMBLY DRAWING - BOTTOM

FPGA

MARK-1

ς2012.6.7.α

MECHANICAL NOTES

